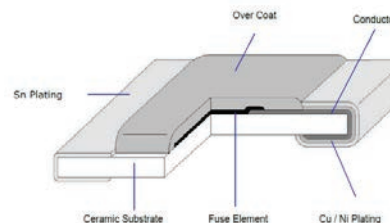


MATERIAL DECLARATION SHEET



Material Number	SF-1206SP		
Product Line	Lead Free Thin Film Chip Fuse		
Compliance Date	2017/07/05		
RoHS Compliant	Yes	MSL	1



No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	0.00454625220	Aluminum oxide	1344-28-1	96%	82.66%	86.10%
				Quartz	14808-60-7	3%	2.58%	
				Magnesium oxide	1309-48-4	1%	0.86%	
2	Inner Conductor	Titanium Tungsten Copper	0.00002587298	Titanium	7440-32-6	13.5%	0.07%	0.49%
				Tungsten	7440-33-7	1.5%	0.01%	
				Copper	7440-50-8	85%	0.42%	
3	Isolation	Quartz	0.00003379328	Quartz	14808-60-7	100%	0.64%	0.64%
4	Fuse Element	Copper	0.00002112080	Copper	7440-50-8	90%	0.36%	0.40%
		Tin		Tin	7440-31-5	10%	0.04%	
5	Over-Coating	Epoxy	0.00015946204	Epoxy	29690-82-2	100%	3.02%	3.02%
6	End Terminal	Nickel Chromium	0.00000528020	Nickel	7440-02-0	80%	0.08%	0.10%
				Chromium	7440-47-3	20%	0.02%	
7	Marking	Epoxy	0.00000686426	Epoxy	25085-99-8	100%	0.13%	0.13%
8	Cu Plating	Copper	0.00021437612	Copper	7440-50-8	100%	4.06%	4.06%
9	Ni Plating	Nickel	0.00014098134	Nickel	7440-02-0	100%	2.67%	2.67%
10	Sn plating	Tin	0.00012619678	Tin	7440-31-5	100%	2.39%	2.39%
TOTAL WEIGHT			0.0052802					

This Document was updated on: 4-25-2018